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# **Surface Mount Ultrafast Power Rectifiers**

Ideally suited for high voltage, high frequency rectification, or as free wheeling and protection diodes in surface mount applications where compact size and weight are critical to the system.

### **Features**

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- High Temperature Glass Passivated Junction
- Low Forward Voltage Drop (0.71 V Max @ 1.0 A, T<sub>J</sub> = 150°C)
- NRVUA and SURA8 Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant\*

## **Mechanical Characteristics:**

- Case: Epoxy, Molded
- Weight: 70 mg (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Polarity Band Indicates Cathode Lead
- ESD Protection:
  - Human Body Model > 4000 V (Class 3)
  - Machine Model > 400 V (Class C)



ON Semiconductor®

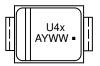
www.onsemi.com

## ULTRAFAST RECTIFIERS 1 AMPERE, 100-200 VOLTS



SMA CASE 403D

#### MARKING DIAGRAM



U4x = Device Code

x = C for MURA115 = D for MURA120

A = Assembly Location

Y = Year WW = Work Week

Pb–Free Package

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>	
MURA115T3G	SMA (Pb-Free)	5,000/Tape & Reel	
MURA120T3G	SMA (Pb-Free)	5,000/Tape & Reel	
NRVUA120VT3G	SMA (Pb-Free)	5,000/Tape & Reel	
SURA8120T3G	SMA (Pb-Free)	5,000/Tape & Reel	

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage MURA115T3G MURA120T3G/SURA8120T3G/NRVUA120VT3G	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	150 200	V	
Average Rectified Forward Current  @ T <sub>L</sub> = 155°C  @ T <sub>L</sub> = 135°C	I <sub>F(AV)</sub>	1.0 2.0	Α	
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I <sub>FSM</sub>	40	Α	
Operating Junction Temperature Range	T <sub>J</sub>	-65 to +175	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Lead (T <sub>L</sub> = 25°C) (Note 1)	Psi <sub>JL</sub> (Note 2)	24	°C/W
Thermal Resistance, Junction-to-Ambient (Note 1)	(Note ∠) R <sub>θJA</sub>	216	

<sup>1.</sup> Rating applies when surface mounted on the minimum pad size recommended, PC Board FR-4.

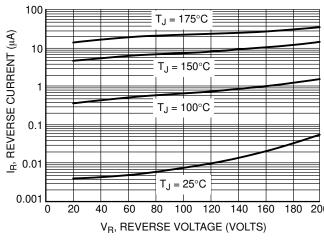
## **ELECTRICAL CHARACTERISTICS**

Characteristic	Symbol	Max	Unit	
Maximum Instantaneous Forward Voltage (Note 3) $(i_F = 1.0 \text{ A}, T_J = 25^{\circ}\text{C})$ $(i_F = 1.0 \text{ A}, T_J = 150^{\circ}\text{C})$	VF	0.875 0.71	V	
Maximum Instantaneous Reverse Current (Note 3) (Rated DC Voltage, $T_J = 25^{\circ}C$ ) (Rated DC Voltage, $T_J = 150^{\circ}C$ )	i <sub>R</sub>	2.0 50	μΑ	
Maximum Reverse Recovery Time (i <sub>F</sub> = 1.0 A, di/dt = 50 A/μs)	t <sub>rr</sub>	35	ns	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 3. Pulse Test: Pulse Width = 300  $\mu$ s, Duty Cycle  $\leq$  2.0%.

<sup>2.</sup> In compliance with JEDEC 51, these values (historically represented by  $R_{\theta JL}$ ) are now referenced as Psi<sub>JL</sub>.

## **TYPICAL CHARACTERISTICS**



T<sub>J</sub> = 175°C

T<sub>J</sub> = 150°C

T<sub>J</sub> = 150°C

T<sub>J</sub> = 150°C

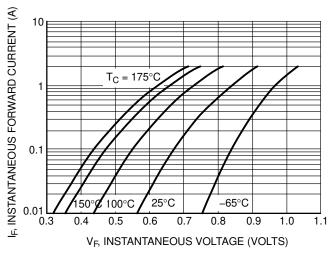
T<sub>J</sub> = 100°C

T<sub>J</sub> = 25°C

V<sub>R</sub>, REVERSE VOLTAGE (VOLTS)

**Figure 1. Typical Reverse Current** 

Figure 2. Maximum Reverse Current





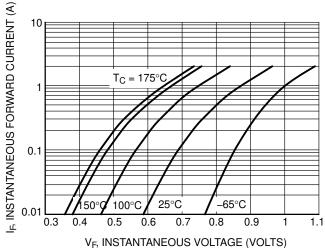


Figure 4. Maximum Forward Voltage

## TYPICAL CHARACTERISTICS

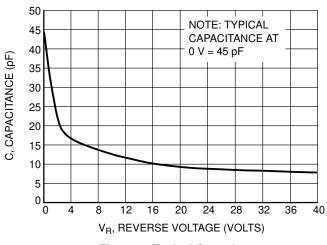


Figure 5. Typical Capacitance

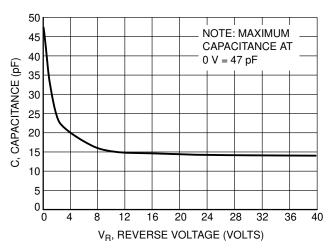


Figure 6. Maximum Capacitance

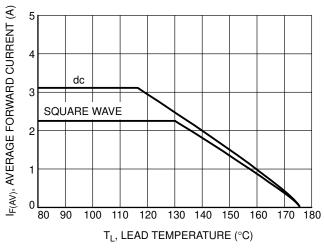


Figure 7. Current Derating, Lead

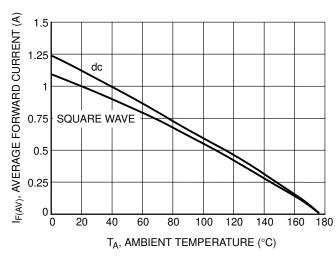


Figure 8. Current Derating, Ambient (FR-4 Board with Minimum Pad)

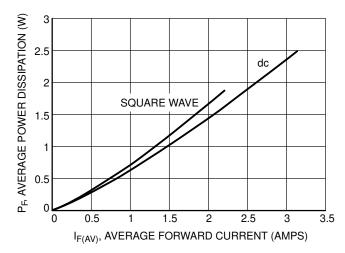
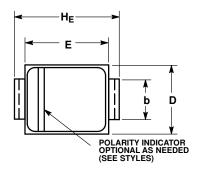


Figure 9. Power Dissipation

### PACKAGE DIMENSIONS

## **SMA** CASE 403D **ISSUE H**



- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

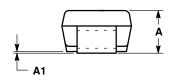
STYLE 1: PIN 1. CATHODE (POLARITY BAND) 2 ANODE

CONTROLLING DIMENSION: INCH.
 DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L.

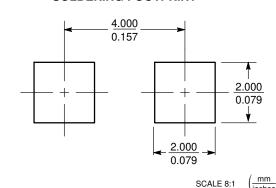
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	MON	MAX
Α	1.97	2.10	2.20	0.078	0.083	0.087
A1	0.05	0.10	0.20	0.002	0.004	0.008
b	1.27	1.45	1.63	0.050	0.057	0.064
C	0.15	0.28	0.41	0.006	0.011	0.016
D	2.29	2.60	2.92	0.090	0.103	0.115
E	4.06	4.32	4.57	0.160	0.170	0.180
HE	4.83	5.21	5.59	0.190	0.205	0.220
L	0.76	1.14	1.52	0.030	0.045	0.060







## SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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